

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT2758955

SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>CHIN-I LIAO</td> <td>03/03/2014</td> </tr> <tr> <td>SHENG-HSU LIU</td> <td>02/20/2014</td> </tr> </tbody> </table>		Name	Execution Date	CHIN-I LIAO	03/03/2014	SHENG-HSU LIU	02/20/2014		
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RECEIVING PARTY DATA									
<table border="1"> <tr> <td>Name:</td> <td>UNITED MICROELECTRONICS CORP.</td> </tr> <tr> <td>Street Address:</td> <td>NO. 3, LI-HSIN RD. II, SCIENCE-BASED INDUSTRIAL PARK</td> </tr> <tr> <td>City:</td> <td>HSINCHU</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> </table>		Name:	UNITED MICROELECTRONICS CORP.	Street Address:	NO. 3, LI-HSIN RD. II, SCIENCE-BASED INDUSTRIAL PARK	City:	HSINCHU	State/Country:	TAIWAN
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CORRESPONDENCE DATA									
<p>Fax Number: (949)660-0809</p> <p>Phone: 9496600761</p> <p>Email: jcpatents@hotmail.com</p> <p><i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i></p> <p>Correspondent Name: J.C. PATENTS</p> <p>Address Line 1: 4 VENTURE, SUITE 250</p> <p>Address Line 4: IRVINE, CALIFORNIA 92618</p>									
ATTORNEY DOCKET NUMBER:	JCLA50727								
NAME OF SUBMITTER:	JIAWEI HUANG								
Signature:	/JIAWEI HUANG/								
Date:	03/07/2014								
This document serves as an Oath/Declaration (37 CFR 1.63).									

PATENT

Total Attachments: 6

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**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

☒ Declaration Submitted With Initial Filing

OR

☐ Declaration Submitted After Initial Filing (surcharge 37 CFR 1.16(f) required)

(Title of the Invention)

**SEMICONDUCTOR DEVICE AND METHOD FOR FABRICATING THE
SAME**

As a below named inventor (hereinafter designated as the undersigned), I hereby
declare that:

This declaration is directed to:

☒ The attached application,

OR

☐ United States Application Number or PCT International application number

_____ Filed on _____

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in
the application.

**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

WHEREAS, the undersigned has invented certain new and useful improvements described in the application identified.

WHEREAS 1. United Microelectronics Corp.
 of No. 3, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan,
 R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring the undersigned's interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by the undersigned, the undersigned has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said the undersigned had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

The undersigned further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

The undersigned hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

UMCD-2013-0825
30727-US-PA

DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION

Signature: C. L. Liao Date: 2014. 3. 3

Legal Name of Sole or First Inventor: Chin-I Liao

Residence: Tainan City, Taiwan

Mailing Address: No.340, Kaisyuan Rd., East District, Tainan City 701, Taiwan, R.O.C.

Signature: _____ Date: _____

Legal Name of Additional Joint Inventor, if any: Sheng-Hsu Liu

Residence: Changhua County, Taiwan

Mailing Address: No.279, Dongfa Rd., Hemei Township, Changhua County 508, Taiwan (R.O.C.)

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NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by the undersigned, the undersigned has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said the undersigned had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

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Residence: Tainan City, Taiwan

Mailing Address: No.340, Kaisyuan Rd., East District, Tainan City 701, Taiwan, R.O.C.

Signature: Sheng-Hsu Liu Date: FEB 20 2014

Legal Name of Additional Joint Inventor, if any: Sheng-Hsu Liu

Residence: Changhua County, Taiwan

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